

SEA & LAND ELECTRONIC CORP.

www.sealand-pptc.com

APPROVAL SHEET

MODEL NO.:	nSMD100-16V
CUSTOMER:	
CUSTOMER'S APPRO	DVAL:
AUTHORIZED SIGNA	TURE/STAMP:
DATE	
DATE	
MANUFACTURER:	
HEAD OFFICE:	
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Submitted by: Approved by:	Jay Chen YC Lin

SEA & LAND ELECTRONIC CORP.

2014/12/25

Approved by: DATE:



Features

- Surface Mount Devices
- Lead free device
 Size 3.2*1.6 mm/0.12*0.06 inch
- Surface Mount packaging
- for automated assembly

Applications

Almost anywhere there is a low voltage power supply, up to 60V and a load to be protected, including: Computer mother board, Modern. USB hub PDAs & Charger, Analog & digital line card Digital cameras, Disk drivers, CD-ROMs,

nSMD100-16V

Performance Specific	Marking	V _{max}	I _{max}	I _{hold}	I _{hold} I _{trip}	Pd	Maximum Time To Trip		Resistance		Agency Approval	
Model	Marking			@25°C	@25°C	Max.	Current	Time	Ri min	R1max	UL	τυν
		(Vdc)	(A)	(A)	(A)	(W)	(A)	(Sec)	(Ω)	(Ω)	0L	101
nSMD100-16V	αH	16.0	100	1.00	1.80	0.6	8.00	0.30	0.055	0.270		
Ihold = Hold Current. Maximum current device will not trip in 25°C still air.												
Itrip = Trip Current. N	1inimum curr	ent at which	the device v	vill always trip	o in 25°C still	air.						
Vmax = Maximum operating voltage device can withstand without damage at rated current (Imax).												
Imax = Maximum fault current device can withstand without damage at rated voltage (Vmax).												
Pd = Power dissipat	tion when de	vice is in the	tripped state	e in 25°C still	l air environm	nent at rated	d voltage.					
Rimin/max = Minimum/Maximum device resistance prior to tripping at 25°C.												
R1 _{max} = Maximum device resistance is measured one hour post reflow.												
CAUTION : Operation beyond the specified ratings may result in damage and possible arcing and flame.												

Environmental Specifications

Test	Conditions	Resistance change		
Passive aging	+85°C, 1000 hrs.	±5% typical		
Humidity aging	+85°C, 85% R.H. , 168 hours	±5% typical		
Thermal shock	+85°C to -40°C, 20 times	±33% typical		
Resistance to solvent	MIL-STD-202, Method 215	No change		
Vibration	MIL-STD-202, Method 201	No change		
Ambient operating conditions :	- 40 °C to 85 °C			
Maximum surface temperature of the device in the tripped state is 125 °C				

Agency Approvals :

UL pending

Regulation/Standard:



2002/95/EC EN14582

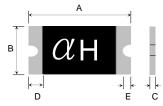
Ihold Versus Temperature

Madal	Maximum ambient operating temperature (T _{mao}) vs. hold current (I _{hold})								
Model	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
nSMD100-16V	1.45	1.31	1.15	1.00	0.84	0.77	0.69	0.61	0.48

nSMD100-16V

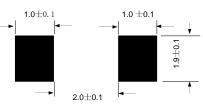
Construction And Dimension (Unit:mm)								
Model	Α		В		С		D	E
INIOUEI	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.
nSMD100-16V	3.00	3.50	1.50	1.80	0.50	1.20	0.15	0.10

Dimensions & Marking



 α = Trademark H = Part identification

Recommended Pad Layout (mm)



Termination Pad Characteristics

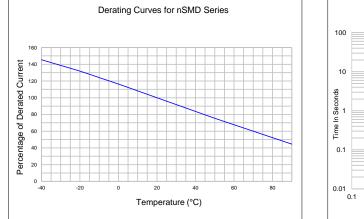
Terminal pad materials : Terminal pad solderability :

Tin-plated Nickel-Copper Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3.

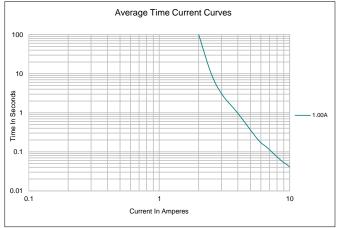
Rework

Use standard industry practices, the removal device must be replaced with a fresh one.

Thermal Derating Curve



Typical Time-To-Trip At 25°C



WARNING:

Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
 PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
 Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
 Use PPTC with a large inductance in circuit will generate a circuit voltage (L di/dt) above the rated voltage of the PPTC.
 Avoid impact PPTC device its hermal expansion like placed under pressure or installed in limited space.
 Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices. PPTC SMD can be cleaned by standard methods.
 Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profile could negatively impact solderability performance of our devices.

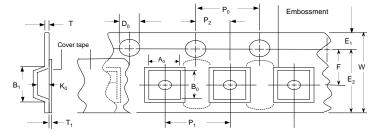
nSMD100-16V

Recommended Solder Reflow Conditions Preheating Soldering Cooling Recommended reflow methods : IR, vapor phase oven, hot air oven. ненденензне(° U) 300 Devices are not designed to be wave soldered to the bottom side 250 of the board. 200 Recommended maximum paste thickness is 0.25 mm (0.010 inch). 190 Devices can be cleaned using standard method and solvents. 160 Note : If reflow temperatures exceed the recommended profile, 100 0 devices may not meet the performance requirements. . 60-120 sec. 30~60sec. 120 sec.

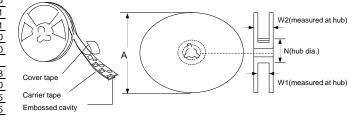
Tape And Reel Specifications (mm)

Governing Specifications	EIA 481-1
W	8.15 ± 0.3
P0	4.0 ± 0.10
P1	4.0 ± 0.10
P2	2.0 ± 0.05
A0	1.95 ± 0.10
B0	3.45 ± 0.10
B1max.	4.35
D0 F	1.5 + 0.1, -0
	3.5 ± 0.05
E1	1.75 ± 0.10
E2min.	6.25
Tmax.	0.6
T1max.	0.1
КО	1.04 ± 0.1
Leader min.	390
Trailer min.	160
Reel Dimensions	
A max.	178
N min.	60
W1	9 ± 0.5
W2	12.6 ± 0.5

EIA Tape Component Dimensions



EIA Reel Dimensions



Storage And Handling

• Storage conditions : 40°C max, 70% R.H.

Devices may not meet specified performance

if storage conditions are exceeded.

Order Information	Packaging				
nSMD	100	-16V	Tape & Reel Quantity		
Product name	Hold	Max			
Size 3216 mm / 1206 inch	Current	Voltage	3500 pcs/reel		
SMD : surface mount device	1.00A				

Tape & reel packaging per EIA481-1

Labeling Information

Sea & Land E	TECHFUSE lectronic Corp.
HF	Pb RoHS
Model:	
Part no.:	
Spec.:	
Lot no.:	
Q'ty:	
『儲: 密封! 溫度: 18~33℃/濕度: :	30∼60% A